

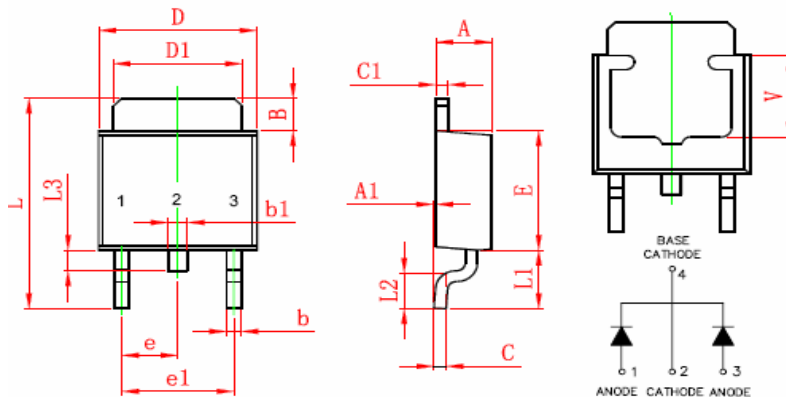
## MBRD3045CT SCHOTTKY RECTIFIER

**Applications:**

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

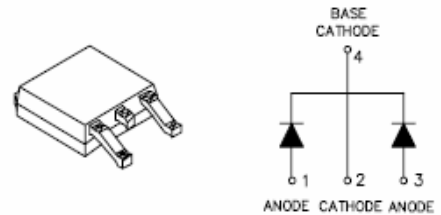
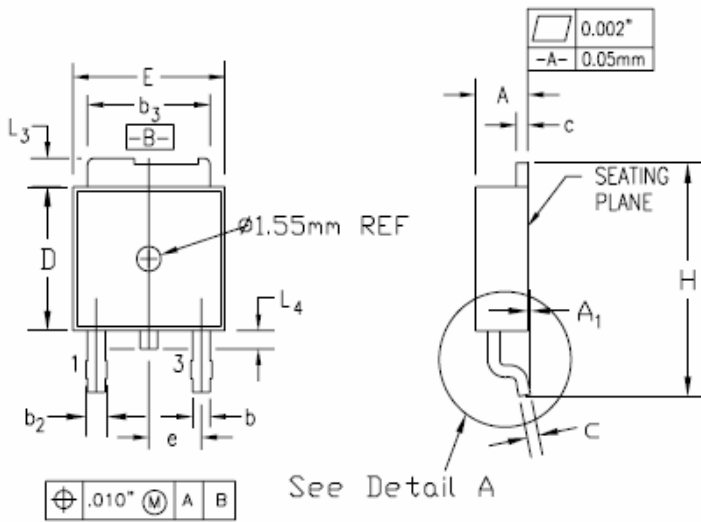
**Features:**

- 150 °C T<sub>J</sub> operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

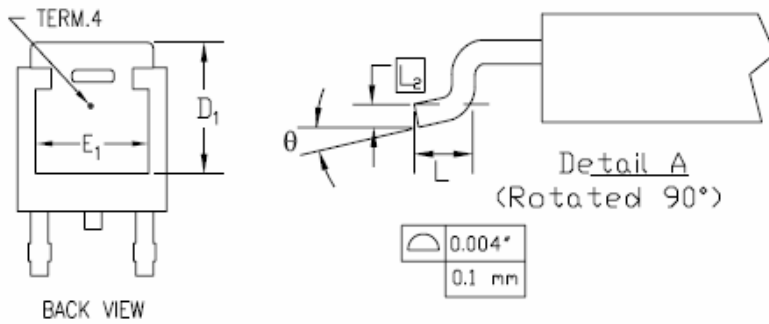
**Mechanical Dimensions: In Inches / mm**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800 REF.		0.150 REF.	

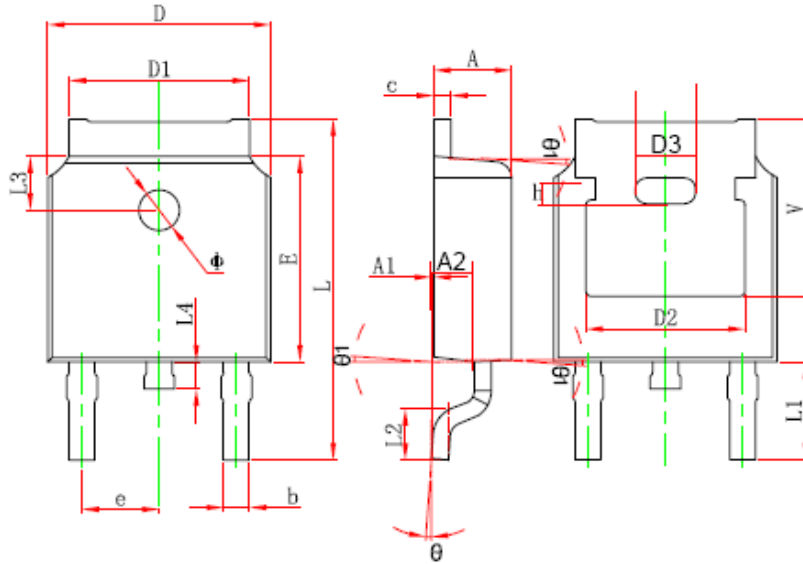
**OPTION 1**



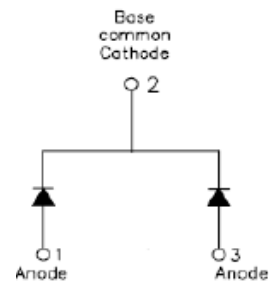
SYMBOL	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.086	0.094	2.19	2.38
A1	—	0.005	—	0.13
b	0.025	0.035	0.64	0.89
b2	0.033	0.045	0.84	1.14
b3	0.205	0.215	5.21	5.46
c	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
D1	0.205	—	5.21	—
E	0.250	0.265	6.35	6.73
E1	0.190	—	4.83	—
e	0.090 BSC		2.29 BSC	
H	0.380	0.410	9.65	10.41
L	0.055	0.070	1.40	1.78
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	0.025	0.040	0.64	1.01
θ	0°	8°	0°	8°



**OPTION 2**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.380	0.087	0.094
A1	0.000	0.100	0.000	0.004
b	0.710	0.810	0.028	0.032
c	0.460	0.560	0.018	0.022
D	6.500	6.700	0.256	0.264
D1	5.130	5.460	0.202	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
A2	0.910	1.110	0.036	0.044
V	5.350 REF.		0.211 REF.	
D3	1.778 REF.		0.070 REF.	
h	0.762 REF.		0.030 REF.	
θ1	7°		7°	



**OPTION 3(CJ)**

**DPAK**

**Marking Diagram:**



Where XXXXX is YYWWL

MBR = Device Type  
D = Package type  
30 = Forward Current (30A)  
45 = Reverse Voltage (45V)  
CT = Configuration  
SSG = SSG  
YY = Year  
WW = Week  
L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

**Ordering Information:**

Device	Package	Shipping
MBRD3045CT	DPAK (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

**Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	$V_{RWM}$	-	45	V
Max. Average Forward	$I_{F(AV)}$	50% duty cycle @ $T_C=123^{\circ}C$ , rectangular wave form	30	A
Max. Peak One Cycle Non-Repetitive Surge Current (per leg)	$I_{FSM}$	8.3 ms, half Sine pulse	240	A

**Electrical Characteristics:**

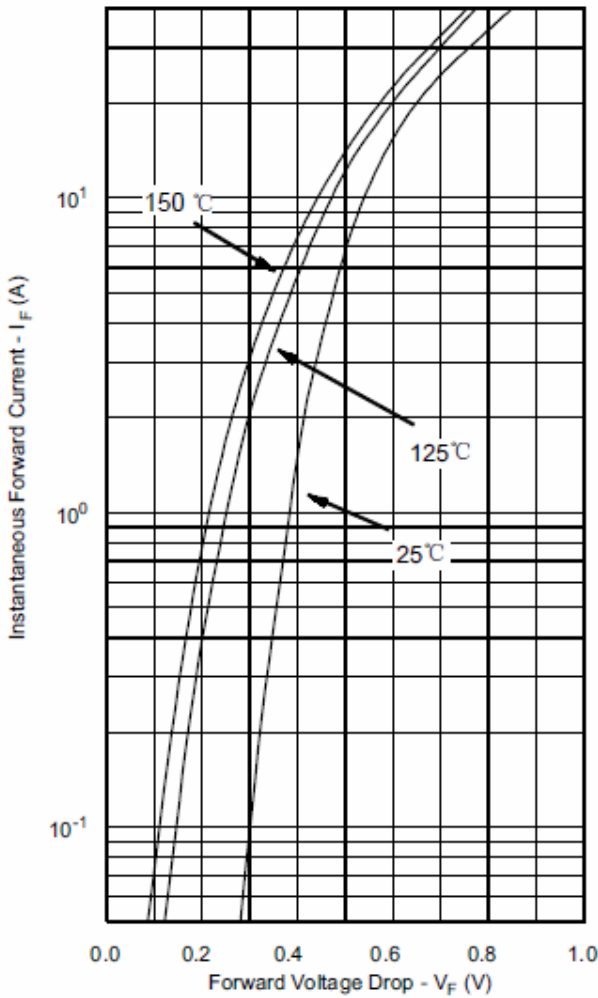
Characteristics	Symbol	Condition	Max.	Units
Max. Forward Voltage Drop *	$V_{F1}$	@ 30 A, Pulse, $T_J = 25\text{ }^\circ\text{C}$	0.84	V
	$V_{F2}$	@ 30 A, Pulse, $T_J = 125\text{ }^\circ\text{C}$	0.72	V
Max. Reverse Current (per leg) *	$I_{R1}$	@ $V_R = \text{rated } V_R$ $T_C = 25\text{ }^\circ\text{C}$	0.2	mA
	$I_{R2}$	@ $V_R = \text{rated } V_R$ $T_C = 125\text{ }^\circ\text{C}$	40	mA
Max. Junction Capacitance (per leg)	$C_T$	@ $V_R = 5\text{V}$ , $T_C = 25\text{ }^\circ\text{C}$ $f_{SIG} = 1\text{MHz}$	500	pF
Max. Voltage Rate of Change	dv/dt	-	10,000	V/ $\mu\text{s}$

\* Pulse Width < 300 $\mu\text{s}$ , Duty Cycle <2%

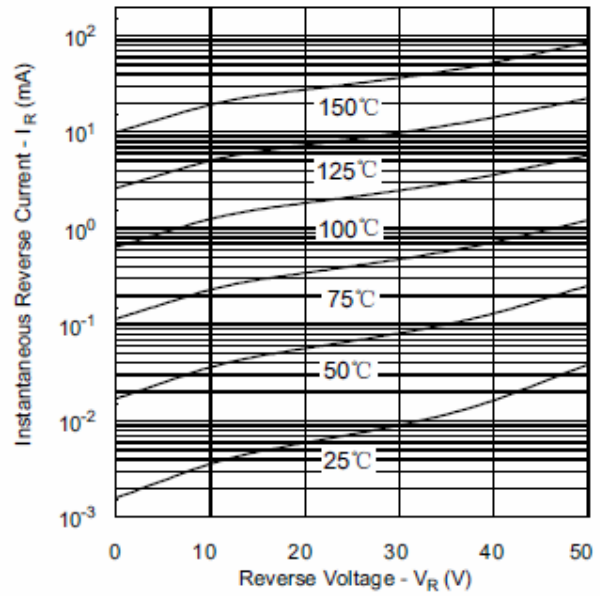
**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature Range	$T_J$	-	-55 to +150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-	-55 to +150	$^\circ\text{C}$
Maximum Thermal Resistance Junction to Case (per leg)	$R_{\theta JC}$	DC operation	4.5	$^\circ\text{C/W}$
Approximate Weight	wt	-	0.39	g
Case Style	DPAK			

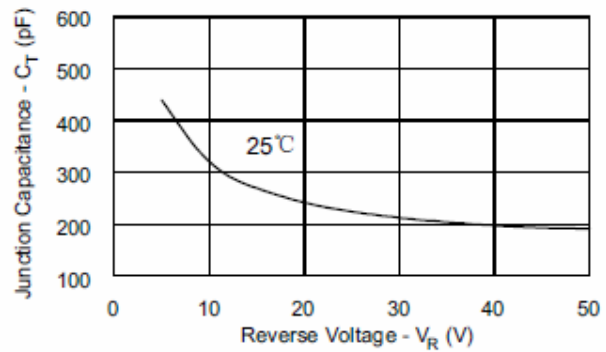
**Typical Forward Characteristics**



**Typical Reverse Characteristics**



**Typical Junction Capacitance**



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